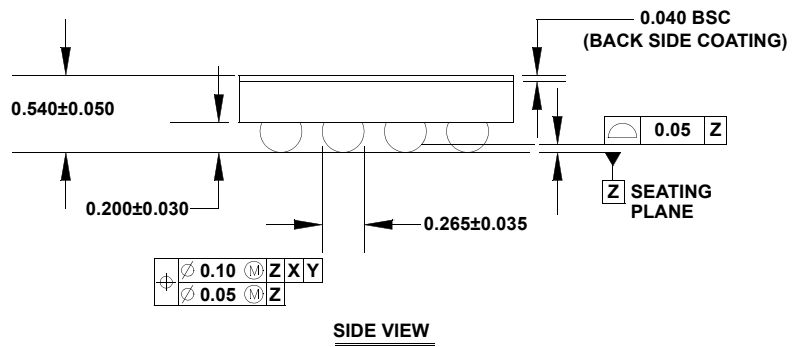
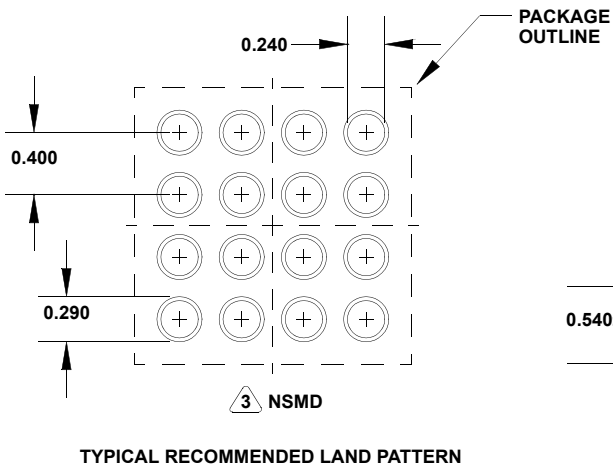
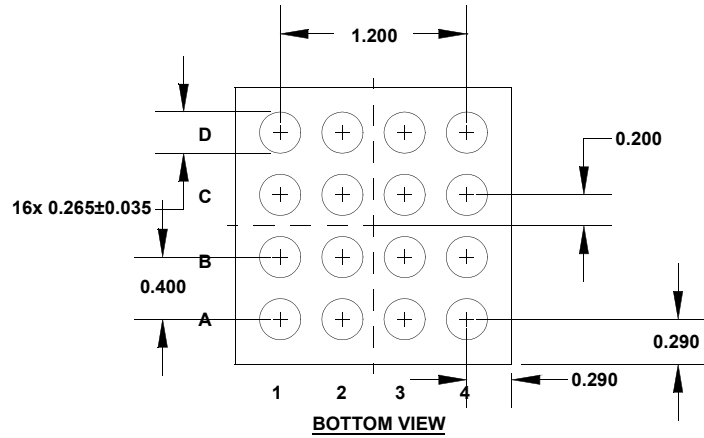
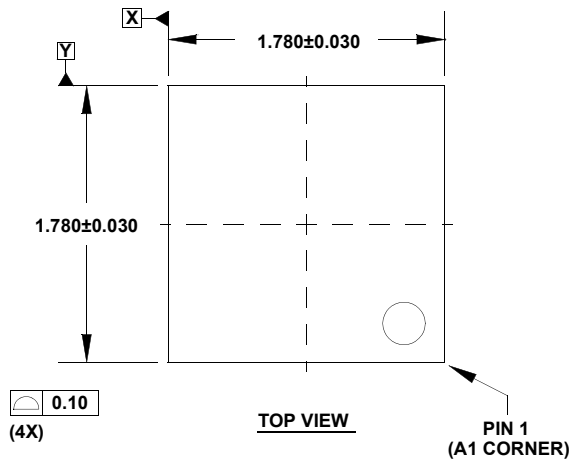


Package Outline Drawing

W4x4.16E

4X4 ARRAY 16 BALLS WITH 0.40 PITCH WAFER LEVEL CHIP SCALE PACKAGE

Rev 0, 2/13



NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance conform to ASMEY14.5-1994, and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per Intersil Technical Brief <http://www.intersil.com/data/tb/tb451.pdf>